

REMARKS

Reconsideration and allowance of the subject patent application are respectfully requested.

Although an amendment presenting claims 1-64 was submitted in the international phase of this application, Applicant's representative confirmed with Examiner Crane that claims 1-64 are not present in the USPTO file for this national stage application (although the fees for these claims were in fact paid). Consequently, the above amendment is made with respect to claims 1-24 currently present in the USPTO file.

Claims 1-24 were rejected under 35 U.S.C. Section 112, second paragraph, as allegedly being indefinite.

The phrase "capable of causing a crack" has been rewritten in claims 1 and 3 to describe that the protection portion is made of a material in which a crack extending to the semiconductor circuit portion is formed after a predetermined means performs. This concept is discussed in connection with the non-limiting, illustrative embodiments at, for example, page 3, lines 20-22; page 24, lines 14-23; and page 25, line 15 to page 26, line 3. These portions of the specification describe by way of example without limitation a protection portion that initially has no crack as shown in Figure 7A. A crack is formed in example protection film 32 after predetermined means performs (e.g., a mechanical punch, heat, pressure, light, etc.) as shown in Figure 7B. Language regarding a crack in a protection portion in claim 23 has been similarly amended for clarification.

The phrase "freely strippable member" in claim 2 has been rewritten to describe a strippable member. This concept is discussed in connection with the non-limiting, illustrative embodiments at, for example, page 4, lines 19-21 and page 24, line 26 to page 25, line 12. These portions of the specification describe by way of example without limitation a seal 33 that initially seals a window portion of a protection film 32 as shown in Figure 8A. The seal is strippable so that it can be stripped off as shown in Figure 8B. Language regarding a seal in claim 22 has also been amended for clarification.

Claims 8, 9, 10 and 24 have been amended to describe that the "performance deterioration material" deteriorates performance of the organic semiconductor after performance deterioration is activated. This concept is discussed in connection with the non-limiting,

illustrative embodiments at, for example, page 5, lines 16-18 and page 19, lines 18-26. These portions of the specification describe by way of example without limitation that the performance deterioration material is material for deteriorating the performance of an organic semiconductor and that such a material may, for example, be included in a semiconductor memory element at the time of manufacture.

Claim 22 has been amended to describe that the starting device is a seal strip off device for stripping off a seal in order to deteriorate a performance of an organic semiconductor by bringing elements outside of the seal (e.g., moisture or oxygen) into contact with the organic semiconductor. See, e.g., page 4, lines 21-24.

Based on the above amendments, withdrawal of the Section 112, second paragraph, rejection is respectfully requested.

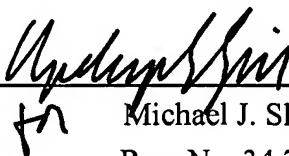
New claims 25-67 have been added. In particular, claims 25-64 are based on the above-mentioned amendment submitted during the international phase of this application, with certain modification to address the Section 112, second paragraph, issues raised in the office action.

The pending claims are believed to be allowable and favorable office action is respectfully requested.

Respectfully submitted,

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